











## PCM5100A, PCM5101A, PCM5102A PCM5100A-Q1, PCM5101A-Q1, PCM5102A-Q1

SLAS859C - MAY 2012 - REVISED MAY 2015

# PCM510xA 2.1 V<sub>RMS</sub>, 112/106/100 dB Audio Stereo DAC with PLL and 32-bit, 384 kHz PCM Interface

## **Features**

- Ultra Low Out-of-Band Noise
- Integrated High-Performance Audio PLL with BCK Reference to Generate SCK Internally
- Direct Line Level 2.1-V<sub>RMS</sub> Output
- No DC Blocking Capacitors Required
- Line Level Output Down to 1KΩ
- Intelligent Muting System; Soft Up or Down Ramp and Analog Mute For 120-dB Mute SNR
- Accepts 16-, 24-, and 32-Bit Audio Data
- PCM Data Formats: I<sup>2</sup>S, Left-Justified
- Automatic Power-Save Mode When LRCK And **BCK Are Deactivated**
- 1.8 V or 3.3 V Failsafe LVCMOS Digital Inputs
- Simple Configuration Using Hardware Pins
- Single-Supply Operation: 14
  - 3.3 V Analog, 1.8 V or 3.3 V Digital
- Qualified in Accordance with AEC-Q100

# Applications

- A/V Receivers, DVD, BD Players
- Automotive Infotainment and Telematics
- **HDTV Receivers**
- Aftermarket Automotive Amplifiers

# Description

The PCM510xA devices are a family of monolithic CMOS-integrated circuits that include a stereo digitalto-analog converter and additional support circuitry in a small TSSOP package. The PCM510xA devices use the latest generation of TI's advanced segment-DAC architecture to achieve excellent dynamic performance and improved tolerance to clock jitter.

Using Directpath™ charge-pump technology, the PCM510xA devices provide 2.1-V<sub>RMS</sub> ground centered outputs, allowing designers to eliminate DC blocking capacitors on the output, as well as external muting circuits traditionally associated with singlesupply line drivers.

The integrated line driver surpasses all other chargepump based line drivers by supporting loads down to 1 k $\Omega$  per pin.

The integrated PLL on the device removes the requirement for a system clock (commonly known as master clock), allowing a 3-wire I<sup>2</sup>S connection and reducing system EMI.

Intelligent clock error and PowerSense undervoltage protection utilizes a two-level mute system for popfree performance.

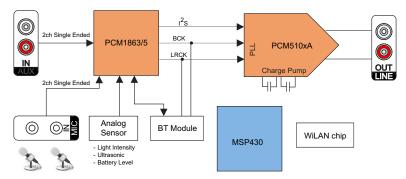
Compared with many conventional switched capacitor DAC architectures, the PCM510xA family offers up to 20 dB lower out-of-band noise, reducing EMI and aliasing in downstream amplifiers/ADCs, measured from the traditional 100-kHz OBN measurements to 3 MHz).

Table 1. Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
PCM5102A		
PCM5101A	TSSOP (20)	5.50 mm × 4.40 mm
PCM5100A		

(1) For all available packages, see the orderable addendum at the end of the data sheet.

# Simplified System Diagram





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	9.3 Feature Description			

# **5 Revision History**

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

CI	nanges from Revision B (January 2015) to Revision C	Page
•	Changed the device number from "PCM510x" to "PCM510xA" in the Simplified System Diagram	1
•	Changed typical performance table to reflect part differences accurately	4
•	Changed "Storage temperatures, T <sub>stg</sub> " to "Operating junction temperature range at –40°C to 130°C"	6
•	Changed "Storage temperature (Q1 devices) –40°C to 125°C" to "Storage temperatures, T <sub>stq</sub> –65°C to 150°C"	
•	Changed the stereo line output load resistance MIN value in the Recommended Operating Conditions from "2 k $\Omega$ " to "1 k $\Omega$ "	
•	Changed the operating junction temperature range in the <i>Recommended Operating Conditions</i> from "MIN = -25°C MAX = 85°C" to "MIN = -40°C MAX = 130°C"	6
•	Added "Q1 Automotive grade devices" and "Consumer grade (non-Q1) devices" to the condition statement in the <i>Electrical Characteristics</i>	7
•	Added "Q1 Automotive grade devices" and "Consumer grade (non-Q1) devices" to the condition statement in the <i>Typical Characteristics</i> graphs section.	12
•	Changed "MCK" to "SCK" at the PLL Clock in the Functional Block Diagram	14
•	Added label "Mute Circuit" and ground symbols to pins DEMP and FMT in Figure 33	26
CI	nanges from Revision A (September 2012) to Revision B	Page
•	Added ESD Rating table, Detailed Description section, Application and Implementation section, Power Supply Recommendations section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information	
•	Added items to show 1.8 V DVDD capability	1
•	Changed the Features list.	1
•	Changed "Operating temperature range " to "Operating junction temperature range"	6
•	Deleted redundant PLL specification in the Recommended Operating Conditions	
•	Deleted "Intelligent clock error" and "for pop-free performance."	14



# PCM5100A, PCM5101A, PCM5102A PCM5100A-Q1, PCM5101A-Q1, PCM5102A-Q1

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•	Clarified clock generation explanation	<u>2</u> 4
•	Clarified external SCK discussion.	25
•	Deleted "The PCM510xA disables the internal PLL when an external SCK is supplied."	25
_	nanges from Original (May 2012) to Revision A	Page
•	Changed layout of first two pages	
•	Changed reference to correct footnote	10
•	Changed t <sub>SCKH</sub> and t <sub>SCKL</sub> values to 9ns	11
•	Removed 48kHz sample rate with PLL-generated clock	25

Submit Documentation Feedback



# 6 Device Comparison

# **Differences Between PCM510xA Devices**

PART NUMBER	DYNAMIC RANGE	SNR	THD
PCM5102A	112dB	112dB	–93 dB
PCM5101A	106 dB	106 dB	−92 dB
PCM5100A	100 dB	100 dB	–90 dB

# **Typical Performance (3.3 V Power Supply)**

	1. 0/
PARAMETER	PCM5102 / PCM5101 / PCM5100
SNR	112 / 106 / 100 dB
Dynamic range	112 /106 / 100 dB
THD+N at -1 dBFS	-93/ -92 / -90 dB
Full-scale single-ended output	2.1 V <sub>RMS</sub> (GND center)
Normal 8x oversampling digital filter latency	20t <sub>S</sub>
Low latency 8x oversampling digital filter latency	3.5t <sub>S</sub>
Sampling frequency	8 kHz to 384 kHz
System clock multiples (f <sub>SCK</sub> ): 64, 128, 192, 256, 384, 512, 768, 1024, 1152, 1536, 2048, 3072	Up to 50 MHz



# 7 Pin Configuration and Functions

# PW 20-Pin Package (Top View) 1 CPVDD DVDD 20 2 CAPP DGND 19 3 CPGND LDOO 18 4 CAPM XSMT 17 5 VNEG FMT 16 6 OUTL LRCK 15

DIN 14

BCK 13 SCK 12 SC

FLT 11

7 OUTR

9 AGND 10 DEMP

8 AVDD

# **Pin Functions**

			Fill I dilictions	
	PIN	TYPE	DESCRIPTION	
NAME	NO.			
AGND	9	_	Analog ground	
AVDD	8	Р	Analog power supply, 3.3 V	
BCK	13	1	Audio data bit clock input <sup>(1)</sup>	
CAPM	4	0	Charge pump flying capacitor terminal for negative rail	
CAPP	2	0	Charge pump flying capacitor terminal for positive rail	
CPGND	3	_	Charge pump ground	
CPVDD	1	Р	Charge pump power supply, 3.3 V	
DEMP	10	1	De-emphasis control for 44.1-kHz sampling rate (1): Off (Low) / On (High)	
DGND	19	_	Digital ground	
DIN	14	1	Audio data input <sup>(1)</sup>	
DVDD	20	Р	Digital power supply, 1.8 V or 3.3 V	
FLT	11	I	Filter select : Normal latency (Low) / Low latency (High)	
FMT	16	1	Audio format selection: I <sup>2</sup> S (Low) / Left-justified (High)	
LDOO	18	Р	Internal logic supply rail terminal for decoupling, or external 1.8 V supply terminal	
LRCK	15	1	Audio data word clock input <sup>(1)</sup>	
OUTL	6	0	Analog output from DAC left channel	
OUTR	7	0	Analog output from DAC right channel	
SCK	12	I	System clock input <sup>(1)</sup>	
VNEG	5	0	Negative charge pump rail terminal for decoupling, -3.3 V	
XSMT	17	I	Soft mute control (1): Soft mute (Low) / soft un-mute (High)	

(1) Failsafe LVCMOS Schmitt trigger input



# 8 Specifications

# 8.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Supply voltage	AVDD, CPVDD, DVDD	-0.3	3.9	
	LDO with DVDD at 1.8 V	-0.3	2.25	
District inner treatment	DVDD at 1.8 V	-0.3	2.25	V
Digital input voltage	DVDD at 3.3 V	-0.3	3.9	
Analog input voltage		-0.3	3.9	
Operating junction temperature range		-40	130	°C
Storage temperature, T <sub>stg</sub>		-65	150	°C

# 8.2 ESD Ratings

			VALUE	UNIT
		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±2000	
V <sub>(ESD)</sub>	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±750	V

<sup>(1)</sup> JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

# 8.3 Recommended Operating Conditions

				MIN	NOM	MAX	UNIT
AVDD	Analog power supply voltage range	Referenced to	VCOM mode	3	3.3	3.46	V
AVDD		AGND <sup>(1)</sup>	VREF mode	3.2	3.3	3.46	V
DVDD	Digital power supply voltage range	Referenced to	1.8 V DVDD	1.65	1.8	1.95	V
טטעט		DGND <sup>(1)</sup>	3.3 V DVDD	3.1	3.3	3.46	
CPVDD	Charge pump supply voltage range	Referenced to C	PGND <sup>(1)</sup>	3.1	3.3	3.46	V
MCLK	Master clock frequency					50	MHz
LOL, LOR	Stereo line output load resistance			1	10		kΩ
C <sub>LOUT</sub>	Digital output load capacitance				10		pF
$T_{J}$	Operating junction temperature range		<u> </u>	-40		130	°C

<sup>(1)</sup> All grounds on board are tied together; they must not differ in voltage by more than 0.2 V max, for any combination of ground signals.

## 8.4 Thermal Information

	THERMAL METRIC(1)	PW	
	THERMAL METRIC <sup>(1)</sup>	20 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	91.2	
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	25.3	
$R_{\theta JB}$	Junction-to-board thermal resistance	42	°C // //
ΨЈΤ	Junction-to-top characterization parameter	1	°C/W
ΨЈВ	Junction-to-board characterization parameter	41.5	
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	_	

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.

<sup>(2)</sup> JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



# 8.5 Electrical Characteristics

Clock multiples: 64, 128, 192, 256, 384, 50		PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
Audio data bit length   Bits   Sampling frequency   Sampling frequency   Sampling frequency   System clock frequency   Siz 768, 1024, 1152, 1538, 2048, or 3072   System clock frequency   Siz 768, 1024, 1152, 1538, 2048, or 3072   System clock frequency   Siz 768, 1024, 1152, 1538, 2048, or 3072   System clock frequency   System clock frequenc		Resolution		16	24	32	Bits		
Sampling frequency	Data Fo	rmat (PCM Mode)							
Clock multiples: 64, 128, 192, 256, 384, 50		Audio data bit length		16	24	32	Bits		
System clock frequency   512, 768, 1024, 1152, 1536, 2048, or 3072   50   MHz	f <sub>S</sub> <sup>(1)</sup>	Sampling frequency		8		384	kHz		
Logic family: 3.3 V LVCMOS compatible	f <sub>SCK</sub>	System clock frequency	512, 768, 1024, 1152, 1536, 2048, or			50	MHz		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Digital I	nput/Output for non-Q1 Consumer Grade D	evices						
Input logic level		Logic family: 3.3 V LVCMOS compatible							
More	V <sub>IH</sub>	Input logic lovel		0.7×DV <sub>DD</sub>					
Input logic current   V <sub>IN</sub> = 0 V	$V_{IL}$	input logic level				$0.3 \times DV_{DD}$	V		
	I <sub>IH</sub>	Innut logic current	$V_{IN} = V_{DD}$			10			
Vol.   Output logic level   I <sub>DL</sub> = 4 mA   0.22xDV <sub>DD</sub>   V	I <sub>IL</sub>	Input logic current	V <sub>IN</sub> = 0 V			-10	μΑ		
Vol.   Output logic level   I <sub>DL</sub> = 4 mA   0.22xDV <sub>DD</sub>   V	V <sub>OH</sub>	Outset Issis Issal	$I_{OH} = -4 \text{ mA}$	0.8×DV <sub>DD</sub>					
Note	V <sub>OL</sub>	Output logic level	I <sub>OL</sub> = 4 mA			0.22×DV <sub>DD</sub>	V		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		Logic family 1.8 V LVCMOS compatible							
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	V <sub>IH</sub>	land lanin land		0.7×DV <sub>DD</sub>					
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	V <sub>IL</sub>	Input logic level				0.3×DV <sub>DD</sub>	V		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	I <sub>IH</sub>	l	$V_{IN} = V_{DD}$			10			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	I <sub>IL</sub>	Input logic current	V <sub>IN</sub> = 0 V			-10	μΑ		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	V <sub>OH</sub>	0.4.4.4.4	$I_{OH} = -2 \text{ mA}$	0.8×DV <sub>DD</sub>					
$ \begin{array}{c c c c} & & & & & & & & & & & & & & & & & & &$	V <sub>OL</sub>	Output logic level	I <sub>OL</sub> = 2 mA			0.22×DV <sub>DD</sub>	V		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	Digital I	nput/Output for Q1 Automotive Grade Device	ces						
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		Logic family: 3.3 V LVCMOS compatible							
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	V <sub>IH</sub>			0.7×DV <sub>DD</sub>			.,		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	V <sub>IL</sub>	Input logic level				0.3×DV <sub>DD</sub>	V		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	I <sub>IH</sub>		$V_{IN} = V_{DD}$			10			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	I <sub>IL</sub>	Input logic current	V <sub>IN</sub> = 0 V			-10	μΑ		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	V <sub>OH</sub>		I <sub>OH</sub> = -4 mA	0.8×DV <sub>DD</sub>					
$ \begin{array}{c c} \text{Logic family 1.8 V LVCMOS compatible} \\ \hline V_{\text{IH}} & \\ V_{\text{IL}} & \\ \hline \\ Input logic level & \\ \hline \\ Input logic current & \\ \hline \\ V_{\text{IN}} = V_{\text{DD}} & \\ \hline \\ V_{\text{IN}} = V_{\text{DD}} & \\ \hline \\ V_{\text{IN}} = 0 \text{ V} & \\ \hline \\ V_{\text{IN}} = 0 \text{ V} & \\ \hline \\ V_{\text{IN}} = 0 \text{ V} & \\ \hline \\ V_{\text{OH}} & \\ \hline $	V <sub>OL</sub>	Output logic level	I <sub>OL</sub> = 4 mA			0.22×DV <sub>DD</sub>	V		
Input logic level									
Input logic level	V <sub>IH</sub>			0.7×DV <sub>DD</sub>			.,		
Input logic current $V_{\text{IN}} = V_{\text{DD}}$ 10 $V_{\text{IN}} = 0 \text{ V}$ 10 $V_{\text{DD}}$ 10 $V_{DD$	V <sub>IL</sub>	Input logic level				0.3×DV <sub>DD</sub>	V		
Input logic current $V_{IN} = 0 V$ $V_{OH}$ Output logic level $I_{OH} = -2 \text{ mA}$ $0.8 \times DV_{DD}$ $V$	I <sub>IH</sub>		$V_{IN} = V_{DD}$			10			
$V_{OH}$ Output logic level $I_{OH} = -2 \text{ mA}$ $0.8 \times DV_{DD}$	I <sub>IL</sub>	Input logic current				-10	μΑ		
Output logic level	V <sub>OH</sub>			0.8×DV <sub>DD</sub>					
$V_{OL}$ $I_{OL} = 2 \text{ mA}$ $0.3 \times DV_{DD}$	V <sub>OL</sub>	Output logic level				0.3×DV <sub>DD</sub>	V		

<sup>(1)</sup> One sample time is defined as the reciprocal of the sampling frequency.  $1t_S = 1/f_S$ 



# **Electrical Characteristics (continued)**

PARAMETER	TEST CONDITI	ONS	MIN	TYP	MAX	UNIT
Dynamic Performance (PCM Mode) <sup>(2)(3)</sup>						
		PCM5102A		-93	-83	dB
	f <sub>S</sub> = 48 kHz	PCM5101A		-92	-82	
THD+N at -1 dBFS <sup>(3)</sup>		PCM5100A		-90	-80	
THD+N at -1 dBF5(-7		PCM5102A		-93		
	$f_S = 96 \text{ kHz}$ and 192 kHz	PCM5101A		-92		
		PCM5100A		-90		
		PCM5102A	106	112		
	EIAJ, A-weighted, f <sub>S</sub> = 48 kHz	PCM5101A	100	106		
D (3)	N IZ	PCM5100A	95	100		
Dynamic range (3)		PCM5102A		112		
	KITZ AITU 192 KITZ	PCM5101A		106		
		PCM5100A		100		
	PO	PCM5102A		112		
	EIAJ, A-weighted, $f_S = 48$ kHz	PCM5101A		106		
C: 1: : : (3)	N IZ	PCM5100A		100		
Signal-to-noise ratio <sup>(3)</sup>		PCM5102A		112		
	EIAJ, A-weighted, f <sub>S</sub> = 96 kHz and 192 kHz	PCM5101A		106		
	KIZ GIG 152 KIZ	PCM5100A		100		
6: 1: : : : : : :	EIAJ, A-weighted, f <sub>S</sub> = 48	kHz	113	123		
Signal to noise ratio with analog mute <sup>(3)(4)</sup>	EIAJ, A-weighted, f <sub>S</sub> = 96 kHz	kHz and 192		123		
		PCM5102A	100	109		
	f <sub>S</sub> = 48 kHz	PCM5101A	95	103		
		PCM5100A	90	97		
		PCM5102A		109		
Channel separation	f <sub>S</sub> = 96 kHz	PCM5101A		103		
		PCM5100A		97		
		PCM5102A		109		
	f <sub>S</sub> = 192 kHz	PCM5101A		103		
		PCM5100A		97		

<sup>(2)</sup> Filter condition: THD+N: 20-Hz HPF, 20-kHz AES17 LPF; Dynamic range: 20-Hz HPF, 20-kHz AES17 LPF; A-weighted signal-to-noise ratio: 20-Hz HPF, 20-kHz AES17 LPF; A-weighted channel separation: 20-Hz HPF, 20-kHz AES17 LPF. Analog performance specifications are measured using the System Two Cascade™ audio measurement system by Audio Precision™ in the RMS mode.

<sup>(3)</sup> Output load is 10 kΩ, with 470-Ω output resistor and a 2.2-nF shunt capacitor (see recommended output filter).

<sup>(4)</sup> Assert XSMT or both L-ch and R-ch PCM data are Bipolar Zero.





# **Electrical Characteristics (continued)**

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Analog C	Output					
	Output voltage			2.1		$V_{RMS}$
	Gain error		-6	±2	6	% of FSR
	Gain error on Q1 Automotive Grade Devices		-7	±2	7	% of FSR
	Gain mismatch, channel-to-channel		-6	±2	6	% of FSR
	Gain mismatch, channel-to-channel on Q1 Devices		-6	±2	6	% of FSR
	PCM5100/1 bipolar zero error	At bipolar zero	-5	±1	5	mV
	PCM5102 Bipolar zero error	At bipolar zero	-2	±1	2	mV
	Load impedance		1			kΩ
Filter Ch	aracteristics-1: Normal		1			
	Pass band				0.45f <sub>S</sub>	
	Stop band		0.55f <sub>S</sub>			
	Stop band attenuation		-60			
	Pass-band ripple				±0.02	dB
	Delay time			20t <sub>S</sub>		s
Filter Ch	aracteristics-2: Low Latency			20.5		
	Pass band				0.47f <sub>S</sub>	
	Stop band		0.55f <sub>S</sub>		0.1115	
	Stop band attenuation		-52			
	Pass-band ripple		-52		±0.0001	dB
	Delay time			2 5+	±0.0001	•
D 0				3.5t <sub>S</sub>		S
	upply Requirements	T+ DV 4.0.V	4.05	4.0	4.05	VDC
DV <sub>DD</sub>	Digital supply voltage	Target DV <sub>DD</sub> = 1.8 V	1.65	1.8	1.95	VDC
DV <sub>DD</sub>	Digital supply voltage	Target DV <sub>DD</sub> = 3.3 V	3	3.3	3.6	1/20
AV <sub>DD</sub>	Analog supply voltage		3	3.3	3.6	VDC
CPV <sub>DD</sub>	Charge-pump supply voltage		3	3.3	3.6	
	(5)	$f_S = 48 \text{ kHz}$		7		
I <sub>DD</sub>	DV <sub>DD</sub> supply current at 1.8 V <sup>(5)</sup>	$f_S = 96 \text{ kHz}$		8		mA
		f <sub>S</sub> = 192 kHz		9		
		$f_S = 48 \text{ kHz}$		7		:
$I_{DD}$	DV <sub>DD</sub> supply current at 1.8 V <sup>(6)</sup>	$f_S = 96 \text{ kHz}$		8		mA
		f <sub>S</sub> = 192 kHz		9		
$I_{DD}$	DV <sub>DD</sub> supply current at 1.8 V <sup>(7)</sup>	Standby		0.3		mA
		$f_S = 48 \text{ kHz}$		7	12	
$I_{DD}$	DV <sub>DD</sub> supply current at 3.3 V <sup>(5)</sup>	$f_S = 96 \text{ kHz}$		8		mA
		$f_S = 192 \text{ kHz}$		9		
		$f_S = 48 \text{ kHz}$		8	13	
$I_{DD}$	DV <sub>DD</sub> supply current at 3.3 V <sup>(6)</sup>	$f_S = 96 \text{ kHz}$		9		mA
		f <sub>S</sub> = 192 kHz		10		
I <sub>DD</sub>	DV <sub>DD</sub> supply current at 3.3 V <sup>(7)</sup>	Standby		0.5	0.8	mA
		f <sub>S</sub> = 48 kHz		11	16	
I <sub>DD</sub>	AV <sub>DD</sub> / CPV <sub>DD</sub> supply current <sup>(5)</sup>	f <sub>S</sub> = 96 kHz		11		mA
		f <sub>S</sub> = 192 kHz		11		

- (5) Input is Bipolar Zero data.
- (6) Input is 1 kHz –1 dBFS data.
- (7) Power Down Mode



# **Electrical Characteristics (continued)**

	PARAMETER	TEST CONDITIONS	MIN TYP	MAX	UNIT
		f <sub>S</sub> = 48 kHz	22	32	
$I_{DD}$	AV <sub>DD</sub> / CPV <sub>DD</sub> supply current <sup>(6)</sup>	$f_S = 96 \text{ kHz}$	22		mA
		f <sub>S</sub> = 192 kHz	22		
I <sub>DD</sub>	AV <sub>DD</sub> / CPV <sub>DD</sub> supply current <sup>(7)</sup>	$f_S = n/a$	0.2	0.4	mA
		$f_S = 48 \text{ kHz}$	49	185	
	Power dissipation, DV <sub>DD</sub> = 1.8 V <sup>(5)</sup>	f <sub>S</sub> = 96 kHz	51		mW
		f <sub>S</sub> = 192 kHz	53		
		f <sub>S</sub> = 48 kHz	85	187	
	Power dissipation, DV <sub>DD</sub> = 1.8 V <sup>(6)</sup>	f <sub>S</sub> = 96 kHz	87		mW
		f <sub>S</sub> = 192 kHz	89		
	Power dissipation, DV <sub>DD</sub> = 1.8 V <sup>(7)</sup>	f <sub>S</sub> = n/a (Power Down Mode)	1		mW
		f <sub>S</sub> = 48 kHz	60	92.4	
	Power dissipation, $DV_{DD} = 3.3 V^{(5)}$	f <sub>S</sub> = 96 kHz	63		mW
		f <sub>S</sub> = 192 kHz	66		
		f <sub>S</sub> = 48 kHz	99	148.5	
	Power dissipation, DV <sub>DD</sub> = 3.3 V <sup>(6)</sup>	f <sub>S</sub> = 96 kHz	102		mW
		f <sub>S</sub> = 192 kHz	106		
	Power dissipation, DV <sub>DD</sub> = 3.3 V <sup>(7)</sup>	f <sub>S</sub> = n/a (Power Down Mode)	2	4	mW



# 8.6 Timing Requirements

Figure 1 shows the timing requirements for the system clock input. For optimal performance, use a clock source with low phase jitter and noise.

prised jitter and recor						
		MIN	TYP	MAX	UNIT	
System clock pulse cycle time		20		1000	ns	
Custom alcole mules width I limb	DVDD = 1.8 V	8			ns	
System clock pulse width, High	DVDD = 3.3 V	9				
$t_{SCKL}$ System clock pulse width, Low $\frac{DVDD = 1.8 \text{ V}}{DVDD = 3.3 \text{ V}}$	DVDD = 1.8 V	8				
	9			ns		
	System clock pulse cycle time  System clock pulse width, High	System clock pulse cycle time  System clock pulse width, High  DVDD = 1.8 V  DVDD = 3.3 V  DVDD = 1.8 V	MIN           System clock pulse cycle time         20           System clock pulse width, High         DVDD = 1.8 V         8           DVDD = 3.3 V         9           DVDD = 1.8 V         8	Name	MIN TYP MAX	

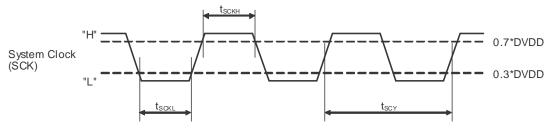


Figure 1. Timing Requirements for SCK Input

# 8.7 Timing Requirements, XSMT

		MIN	TYP	MAX	UNIT
t <sub>r</sub>	Rise time			20	ns
t <sub>f</sub>	Fall time			20	ns

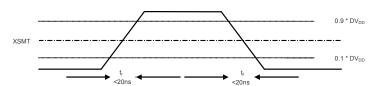
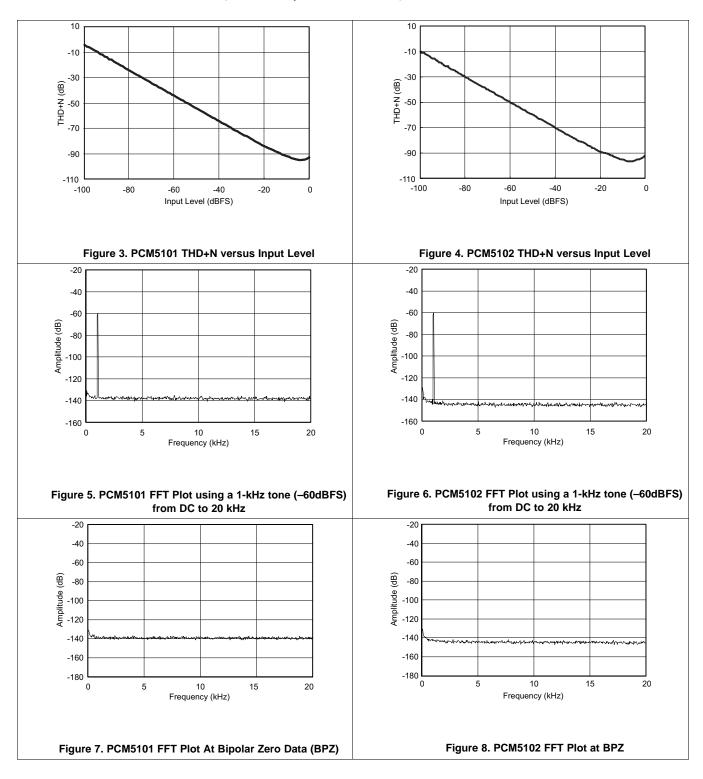


Figure 2. XSMT Timing for Soft Mute and Soft Un-Mute



# 8.8 Typical Characteristics

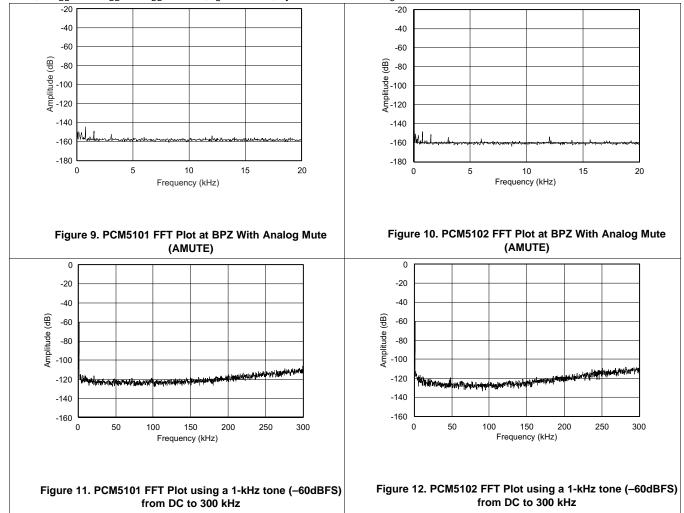
Q1 Automotive grade devices are specified for  $T_A = -40^{\circ}\text{C}$  to 125°C. Consumer grade (non-Q1) devices are specified at  $T_A = 25^{\circ}\text{C}$ ,  $AV_{DD} = CPV_{DD} = DV_{DD} = 3.3 \text{ V}$ ,  $f_S = 48 \text{ kHz}$ , system clock = 512  $f_S$  and 24-bit data unless otherwise noted.





# **Typical Characteristics (continued)**

Q1 Automotive grade devices are specified for  $T_A = -40^{\circ}\text{C}$  to 125°C. Consumer grade (non-Q1) devices are specified at  $T_A = 25^{\circ}\text{C}$ ,  $AV_{DD} = CPV_{DD} = DV_{DD} = 3.3 \text{ V}$ ,  $f_S = 48 \text{ kHz}$ , system clock = 512  $f_S$  and 24-bit data unless otherwise noted.





# 9 Detailed Description

## 9.1 Overview

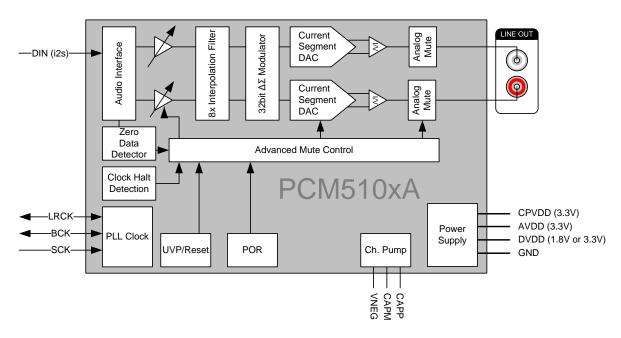
The integrated PLL on the device provided adds the flexibility to remove the system clock (commonly known as master clock), allowing a 3-wire I<sup>2</sup>S connection and reducing system EMI.

Powersense undervoltage protection utilizes a two-level mute system. Upon clock error or system power failure, the device digitally attenuates the data (or last known good data) and then mutes the analog circuit.

Compared with existing DAC technology, the PCM510xA devices offer up to 20 dB lower out-of-band noise, reducing EMI and aliasing in downstream amplifiers/ADCs. (from traditional 100-kHz OBN measurements to 3 MHz).

The PCM510xA devices accept industry-standard audio data formats with 16- to 32-bit data. Sample rates up to 384 kHz are supported.

# 9.2 Functional Block Diagram



# 9.3 Feature Description

# 9.3.1 Terminology

Sampling frequency is symbolized by  $f_S$ . Full scale is symbolized by FS. Sample time as a unit is symbolized by  $t_S$ .

## 9.3.2 Audio Data Interface

## 9.3.2.1 Audio Serial Interface

The audio interface port is a 3-wire serial port with the signals LRCK, BCK, and DIN. BCK is the serial audio bit clock, used to clock the serial data present on DIN into the serial shift register of the audio interface. Serial data is clocked into the PCM510xA on the rising edge of BCK. LRCK is the serial audio left/right word clock. LRCK polarity for left/right is given by the format selected.



# **Feature Description (continued)**

Table 2. PCM510xA Audio Data Formats, Bit Depths and Clock Rates

CONTROL MODE	FORMAT	DATA BITS	MAX LRCK FREQUENCY [f <sub>S</sub> ]	SCK RATE [x f <sub>S</sub> ]	BCK RATE [x f <sub>S</sub> ]
Hardware Control	l <sup>2</sup> S/LJ	32, 24, 20, 16	Up to 192 kHz	128 – 3072 (≤50MHz)	64, 48, 32
riarawaro control	. 5, 25	- , , -, -	384 kHz	64, 128	64, 48, 32

The PCM510xA requires the synchronization of LRCK and system clock, but does not need a specific phase relation between LRCK and system clock.

If the relationship between LRCK and system clock changes more than ±5 SCK, internal operation (using an onchip oscillator) is initialized within one sample period and analog outputs are forced to the bipolar zero level until resynchronization between LRCK and system clock is completed.

If the relationship between LRCK and BCK are invalid more than 4 LRCK periods, internal operation (using an onchip oscillator) is initialized within one sample period and analog outputs are forced to the bipolar zero level until resynchronization between LRCK and BCK is completed.

## 9.3.2.2 PCM Audio Data Formats

The PCM510xA supports industry-standard audio data formats, including standard I<sup>2</sup>S and left-justified. Data formats are selected using the FMT (pin 16), Low for I<sup>2</sup>S, and High for Left-justified. All formats require binary twos-complement, MSB-first audio data; up to 32-bit audio data is accepted.

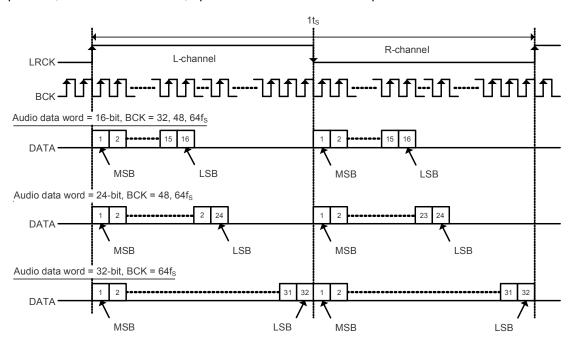
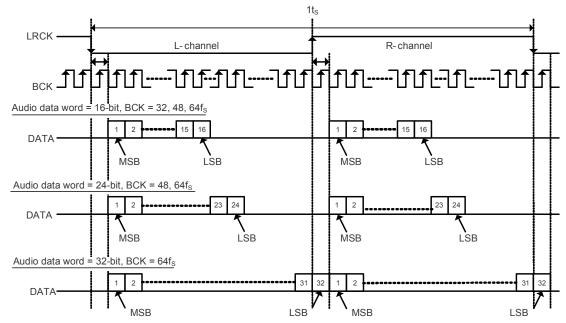


Figure 13. Left Justified Audio Data Format





I<sup>2</sup>S Data Format; L-channel = LOW, R-channel = HIGH

Figure 14. I<sup>2</sup>S Audio Data Format

## 9.3.2.3 Zero Data Detect

The PCM510xA has a zero-data detect function. When the device detects continuous zero data, it enters a full analog mute condition. The PCM510xA counts zero data over 1024 LRCKs (21ms @ 48kHz) before setting analog mute.

In Hardware mode, the device uses default values. By default, Both L-ch and R-ch have to be zero data for zero data detection to begin the muting process etc.

# 9.3.3 XSMT Pin (Soft Mute / Soft Un-Mute)

An external digital host controls the PCM510xA soft mute function by driving the XSMT pin with a specific minimum rise time  $(t_r)$  and fall time  $(t_f)$  for soft mute and soft un-mute. The PCM510xA requires  $t_r$  and  $t_f$  times of less than 20ns. In the majority of applications, this is no problem, however, traces with high capacitance may have issues.

When the XSMT pin is shifted from high to low (3.3 V to 0 V), a soft digital attenuation ramp begins. -1-dB attenuation is then applied every sample time from 0 dBFS to  $-\infty$ . The soft attenuation ramp takes 104 samples.

When the XSMT pin is shifted from low to high (0 V to 3.3 V), a soft digital "un-mute" is started. 1-dB gain steps are applied every sample time from  $-\infty$  to 0 dBFS. The un-mute takes 104 samples.

In systems where XSMT is not required, it can be directly connected to AVDD.



# 9.3.4 Audio Processing

# 9.3.4.1 Interpolation Filter

The PCM510xA provides two types of interpolation filter. Users can select which filter to use by using the FLT pin (pin 11).

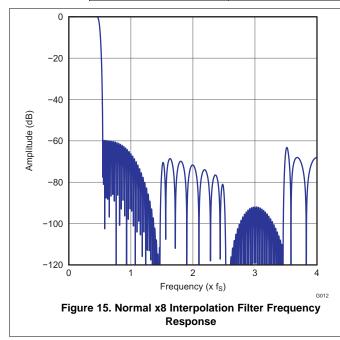
**Table 3. Digital Interpolation Filter Options** 

FLT Pin	Description
0	FIR normal x8/x4/x2/x1 interpolation filters
1	IIR low-latency x8/x4/x2/x1 interpolation filters

The normal x8 / x4 / x2 / x1(bypass) interpolation filter is programmed for sample rates from 8 kHz to 384 kHz.

Table 4. Normal x8 Interpolation Filter

Parameter	Condition	Value (Typ)	Value (Max)	Units
Filter gain pass band	0 0.45f <sub>S</sub>		±0.02	dB
Filter gain stop band	0.55f <sub>S</sub> 7.455f <sub>S</sub>	-60		dB
Filter group delay		22t <sub>S</sub>		s



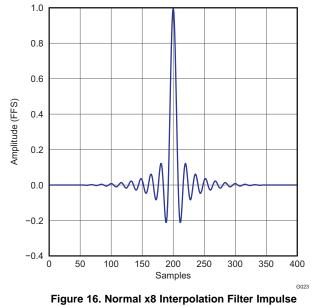
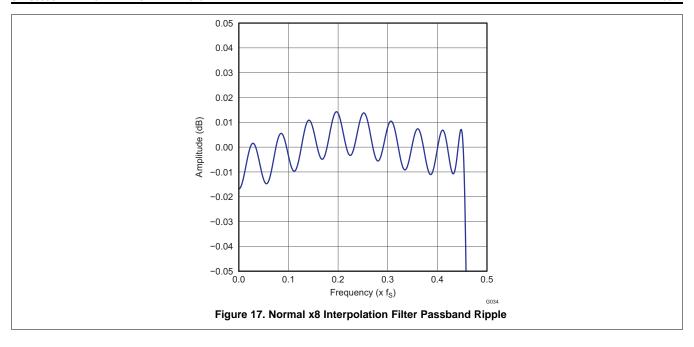


Figure 16. Normal x8 Interpolation Filter Impulse Response



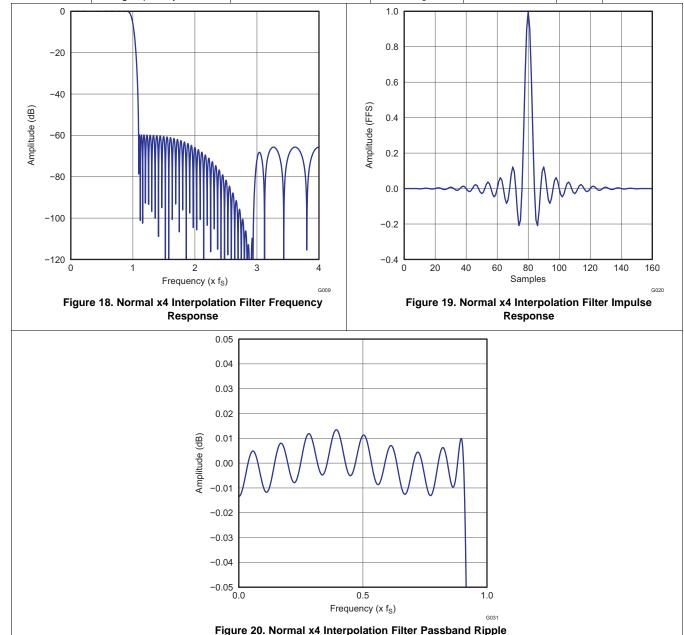




The normal x4 / x2 / x1 (bypass) interpolation filter is programmed for sample rates from 8 kHz to 384 kHz.

# Table 5. Normal x4 Interpolation Filter

Parameter	Condition	Value (Typ)	Value (Max)	Units
Filter gain pass band	0 0.45f <sub>S</sub>		±0.02	dB
Filter gain stop band	0.55f <sub>S</sub> 7.455f <sub>S</sub>	-60		dB
Filter group delay		22t <sub>S</sub>		S





# Table 6. Normal x2 Interpolation Filter

Parameter	Condition	Value (Typ)	Value (Max)	Units
Filter gain pass band	0 0.45f <sub>S</sub>		±0.02	dB
Filter gain stop band	0.55f <sub>S</sub> 7.455f <sub>S</sub>	-60		dB
Filter group delay		22t <sub>S</sub>		S

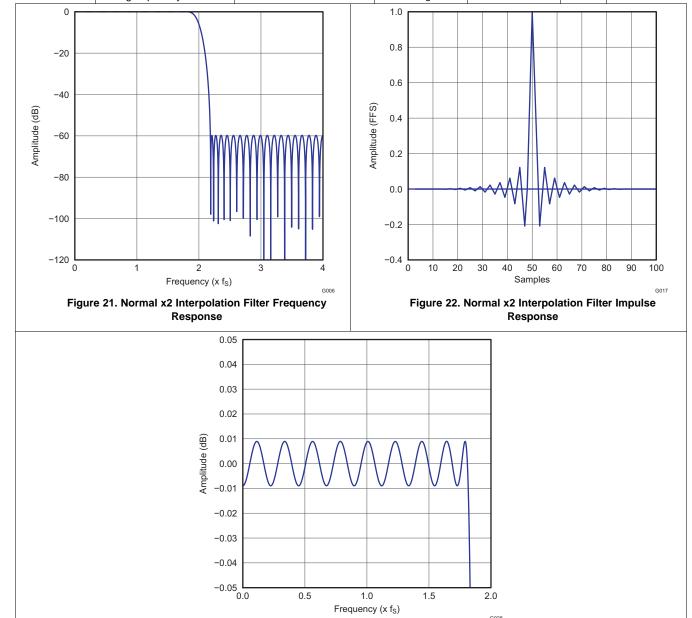


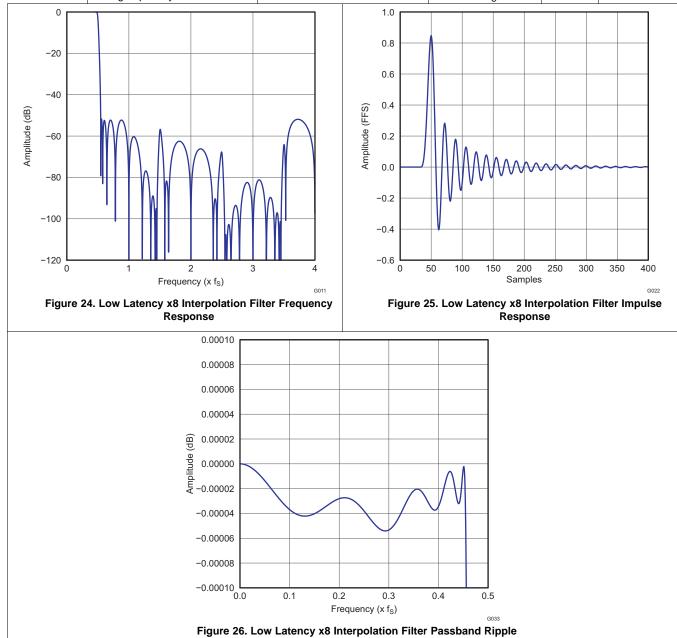
Figure 23. Normal x2 Interpolation Filter Passband Ripple



The low-latency x8 / x4 / x2 / x1 (bypass) interpolation filter is programmed for sample rates from 8 kHz to 384 kHz

Table 7. Low Latency x8 Interpolation Filter

Parameter	Condition	Value (Typ)	Units
Filter gain pass band	0 0.45f <sub>S</sub>	±0.0001	dB
Filter gain stop band	0.55f <sub>S</sub> 7.455f <sub>S</sub>	-52	dB
Filter group delay		3.5t <sub>s</sub>	S

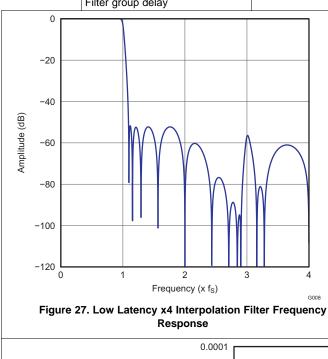




# Table 8. Low Latency x4 Interpolation Filter

Parameter	Condition	Value (Typ)	Units
Filter gain pass band	0 0.45f <sub>S</sub>	±0.0001	dB
Filter gain stop band	0.55f <sub>S</sub> 3.455f <sub>S</sub>	-52	dB
Filter group delay		3.5t <sub>S</sub>	S

1.0



8.0 0.6 0.4 Amplitude (FFS) 0.2 0.0 -0.2-0.4 -0.6 20 40 60 80 100 120 140 160 180 Samples

Figure 28. Low Latency x4 Interpolation Filter Impulse Response

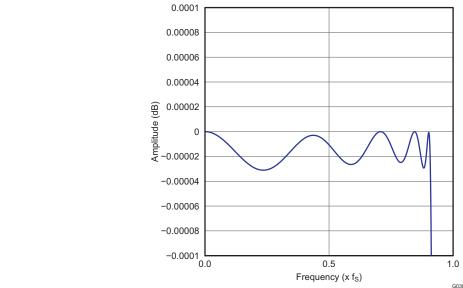
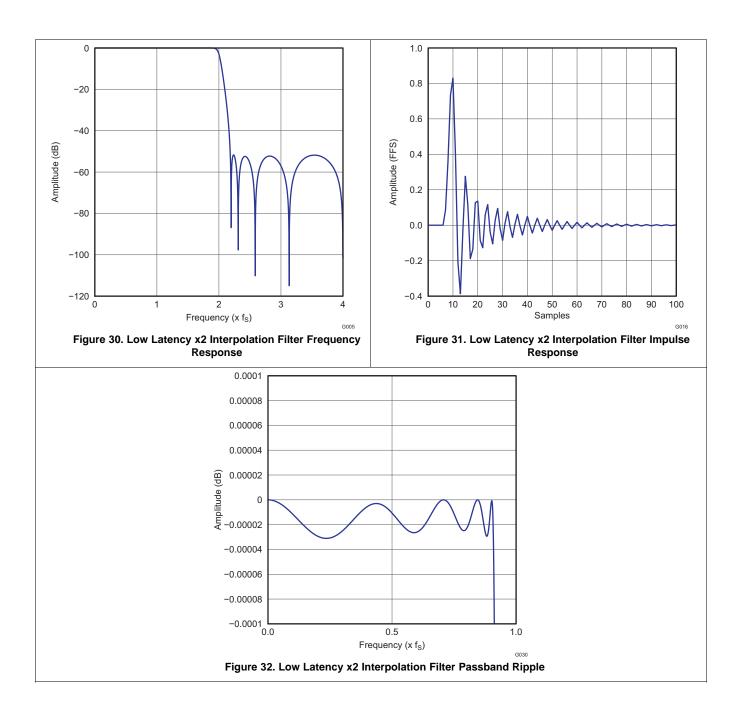


Figure 29. Low Latency x4 Interpolation Filter Passband Ripple



# Table 9. Low Latency x2 Interpolation Filter

Parameter	Condition	Value (Typ)	Units
Filter gain pass band	0 0.45f <sub>S</sub>	±0.0001	dB
Filter gain stop band	0.55f <sub>S</sub> 1.455f <sub>S</sub>	-52	dB
Filter group delay		3.5t <sub>S</sub>	s





## 9.3.5 Reset and System Clock Functions

## 9.3.5.1 Clocking Overview

The PCM510xA devices have flexible systems for clocking. Internally, the device requires a number of clocks, mostly at related clock rates to function correctly. All of these clocks can be derived from the serial audio interface in one form or another.

The data flows at the sample rate ( $f_S$ ). Once the data is brought into the serial audio interface, it gets processed, interpolated and modulated all the way to 128 ×  $f_S$  before arriving at the current segments for the final digital to analog conversion.

The serial audio interface typically has 4 connections SCK (system master clock), BCK (bit clock), LRCK (left right word clock) and DIN (data). The device has an internal PLL that is used to take either SCK or BCK and create the higher rate clocks required by the interpolating processor and the DAC clock. This allows the device to operate with or without an external SCK.

# 9.3.5.2 Clock Slave Mode With Master/System Clock (SCK) Input (4 Wire $l^2$ S)

The PCM510xA requires a system clock to operate the digital interpolation filters and advanced segment DAC modulators. The system clock is applied at the SCK input and supports up to 50 MHz. The PCM510xA system-clock detection circuit automatically senses the system-clock frequency. Common audio sampling frequencies in the bands of 8 kHz, 16 kHz, (32 kHz - 44.1 kHz - 48 kHz), (88.2kHz - 96kHz), (176.4 kHz - 192 kHz), and 384 kHz with ±4% tolerance are supported. Values in the parentheses are grouped when detected, e.g. 88.2kHZ and 96kHz are detected as "double rate," 32kHz, 44.1kHz and 48kHz will be detected as "single rate".

The sampling frequency detector sets the clock for the digital filter, Delta Sigma Modulator (DSM) and the Negative Charge Pump (NCP) automatically. Table 10 shows examples of system clock frequencies for common audio sampling rates.

SCK rates that are not common to standard audio clocks, between 1 MHz and 50 MHz, are only supported in software mode, available only in the PCM512x, PCM514x, and PCM5242 devices, by configuring various PLL and clock-divider registers. This programmability allows the device to become a clock master and drive the host serial port with LRCK and BCK, from a non-audio related clock (for example, using 12 MHz to generate 44.1 kHz [LRCK] and 2.8224 MHz [BCK]).

System Clock Frequency (f<sub>SCK</sub>) (MHz) Sampling Frequency 64 f<sub>S</sub> 128 f<sub>S</sub> 192 f<sub>S</sub> 256 f<sub>S</sub> 384 f<sub>S</sub> 512 f<sub>S</sub> 768 f<sub>S</sub> 1024 f<sub>S</sub> 1152 f<sub>S</sub> 1536 f<sub>S</sub> 2048 f<sub>S</sub> 3072 f<sub>S</sub> \_(1) 1.024(2) 1.536<sup>(2)</sup> 6.144 8 kHz 2.048 3.072 4.096 8.192 12.288 16.384 24.576 9.216 \_(1) 16 kHz 2.048(2) 3.072(2) 4.096 6.144 8.192 12.288 16.384 18.432 24.576 36.864 49.152 \_(1) 4.096(2) \_(1) \_(1) 32 kHz 6.144<sup>(2)</sup> 8.192 12.288 16.384 24.576 32,768 36.864 49.152 \_(1) 5.6488(2) 8.4672(2) 45.1584 \_(1) \_(1) \_(1) \_(1) 44.1 kHz 11.2896 16.9344 22.5792 33.8688 (1) (1) (1) (1) 6.144(2) 9.216(2) (1) 48 kHz 12.288 18.432 24.576 36.864 49.152 \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) 11.2896(2) 88.2 kHz 16.9344 22.5792 33.8688 45.1584 \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) 96 kHz 12.288<sup>(2)</sup> 18.432 24.576 36.864 49.152 \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) 176.4 kHz 22.579 33.8688 45.1584 \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) (1) \_(1) 192 kHz 24.576 36.864 49.152 \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) \_(1) 384 kHz 24.576 49.152

Table 10. System Master Clock Inputs for Audio Related Clocks

(2) This system clock rate is supported by PLL mode.

<sup>(1)</sup> This system clock rate is not supported for the given sampling frequency.



## 9.3.5.3 Clock Slave Mode with BCK PLL to Generate Internal Clocks (3-Wire PCM)

The system clock PLL mode allows designers to use a simple 3-wire I<sup>2</sup>S audio source. The 3-wire source reduces the need for a high frequency SCK, making PCB layout easier, and reduces high frequency electromagnetic interference.

The internal PLL is disabled as soon as an external SCK is supplied.

The device starts up expecting an external SCK input, but if BCK and LRCK start correctly while SCK remains at ground level for 16 successive LRCK periods, then the internal PLL starts, automatically generating an internal SCK from the BCK reference. Specific BCK rates are required to generate an appropriate master clock. Table 11 describes the minimum and maximum BCK per LRCK for the integrated PLL to automatically generate an internal SCK.

Table 11. BCK Rates (MHz) by LRCK Sample Rate for PCM510xA PLL Operation

	BCK (f <sub>S</sub> )						
Sample f (kHz)	32	64					
8	-	-					
16	-	1.024					
32	1.024	2.048					
44.1	1.4112	2.8224					
48	1.536	3.072					
96	3.072	6.144					
192	6.144	12.288					
384	12.288	24.576					

# 9.4 Device Functional Modes

#### 9.4.1 External SCK and PLL Activation

As discussed in *Clock Slave Mode with BCK PLL to Generate Internal Clocks (3-Wire PCM)*, the internal PLL of a PCM510xA device supplies a SCK if an external SCK is not present at powerup.

## 9.4.1.1 Interpolation Filter Modes

Interpolation-filter options are controlled by the FLT pin. See Table 3.

#### 9.4.1.2 44.1kHz De-emphasis

De-emphasis control for 44.1-kHz f<sub>S</sub> is controlled by the DEMP pin. See *Pin Configuration and Functions*.

# 9.4.1.3 Audio Format

Audio format is selected by the FMT pin. See Pin Configuration and Functions.

# 10 Applications and Implementation

#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

# 10.1 Application Information

# 10.1.1 Typical Applications

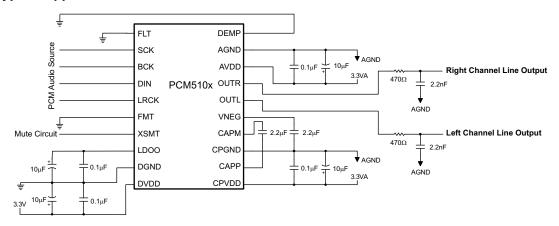


Figure 33. Simplified Schematic, Hardware-Controlled Subsystem

## 10.1.1.1 Example Design Requirements

- · Device control method: hardware control
  - Normal filter latency
  - I<sup>2</sup>S digital audio interface
  - Power rail monitoring from the system 12-V rail to mute early on system power loss
- Single-ended 2.1-V<sub>RMS</sub> analog outputs
- 3-wire I<sup>2</sup>S interface (BCK PLL)
- Single 3.3-V supply

# 10.1.1.2 Detailed Design Procedure

- Device control method: See Pin Configuration and Functions and Audio Processing.
  - Normal filter latency: FLT pin tied low
  - Audio format selection: FMT pin tied low
- Clock and PLL setup (See Reset and System Clock Functions). Ensure incoming BCK meets minimum requirements.
- XSMT pin setup for 12-V monitoring (See External Power Sense Undervoltage Protection Mode).
- Single-supply 3.3-V operation (See Setting Digital Power Supplies and I/O Voltage Rails)



# **Application Information (continued)**

# 10.1.1.3 Application Curve

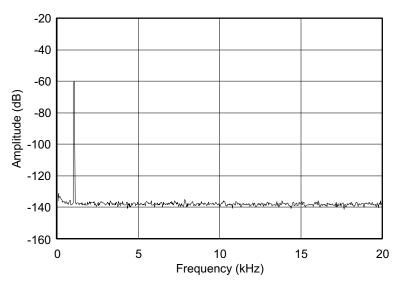


Figure 34. PCM5101A FFT Plot, DC to 20 kHz with a 1 kHz, -60dBFS Input



# 11 Power Supply Recommendations

# 11.1 Power Supply Distribution and Requirements

The PCM510xA devices are powered through the following pins:

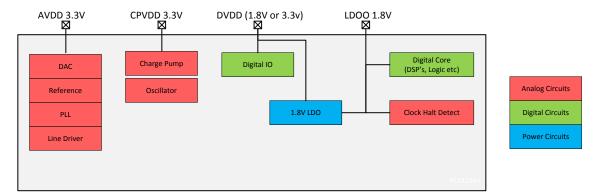


Figure 35. Power Distribution Tree within PCM510xA

**Table 12. Power Supply Pin Descriptions** 

NAME	USAGE / DESCRIPTION
AVDD	Analog voltage supply; must be 3.3 V. This powers all analog circuitry that the DAC runs on.
DVDD	Digital voltage supply. This is used as the I/O voltage control and the input to the onchip LDO.
CPVDD	Charge Pump Voltage Supply - must be 3.3 V
LDOO	Output from the onchip LDO. Should be used with a 0.1-µF decoupling cap. Can be driven (used as power input) with a 1.8-V supply to bypass the onchip LDO for lower power consumption.
AGND	Analog ground
DGND	Digital ground

## 11.2 Recommended Powerdown Sequence

Under certain conditions, the PCM510xA devices can exhibit some pop on power down. Pops are caused by a device not having enough time to detect power loss and start the muting process.

The PCM510xA devices have two auto-mute functions to mute the device upon power loss (intentional or unintentional).

## XSMT = 0

When the XSMT pin is pulled low, the incoming PCM data is attenuated to 0, closely followed by a hard analog mute. This process takes 150 sample times  $(t_s)$  + 0.2 ms.

Because this mute time is mainly dominated by the sampling frequency, systems sampling at 192 kHz will mute much faster than a 48-kHz system.

## **Clock Error Detect**

When clock error is detected on the incoming data clock, the PCM510xA devices switch to an internal oscillator, and continue to the drive the output, while attenuating the data from the last known value. Once this process is complete, the PCM510xA outputs are hard muted to ground.

## 11.2.1 Planned Shutdown

These auto-muting processes can be manipulated by system designs to mute before power loss in the following ways:

1. Assert XSMT low 150 t<sub>S</sub> + 0.2 ms before power is removed.



# Recommended Powerdown Sequence (continued)

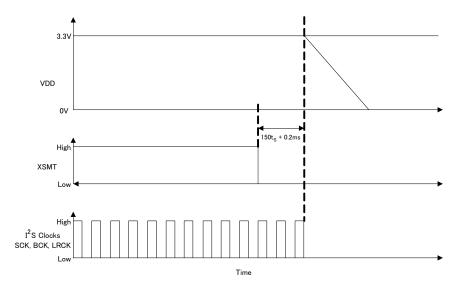


Figure 36. Assert XSMT

2. Stop I<sup>2</sup>S clocks (SCK, BCK, LRCK) 3 ms before powerdown as shown in Figure 37.

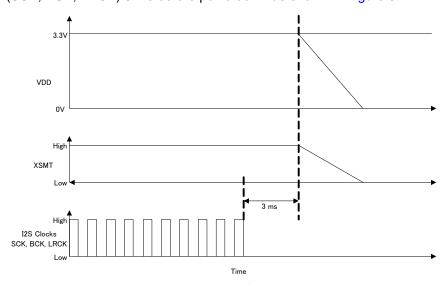


Figure 37. Stop I<sup>2</sup>C Clocks

# 11.2.2 Unplanned Shutdown

Many systems use a low-noise regulator to provide an AVDD 3.3-V supply for the DAC. The XSMT Pin can take advantage of such a feature to measure the pre-regulated output from the system SMPS to mute the output before the entire SMPS discharges. Figure 38 shows how to configure such a system to use the XSMT pin. The XSMT pin can also be used in parallel with a GPIO pin from the system microcontroller/DSP or power supply.



# Recommended Powerdown Sequence (continued)

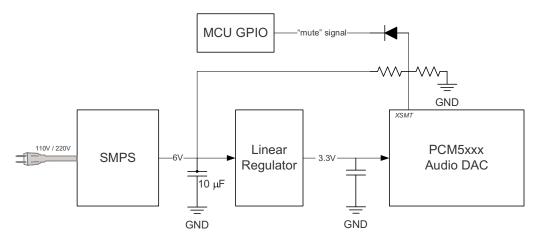


Figure 38. Using the XSMT Pin

# 11.3 External Power Sense Undervoltage Protection Mode

#### NOTE

External Power Sense Undervoltage Protection Mode is supported only when DVDD = 3.3 V.

The XSMT pin can also be used to monitor a system voltage, such as the 24-VDC LCD TV backlight, or 12-VDC system supply using a voltage divider created with two resistors. (See Figure 39)

- If the XSMT pin makes a transition from "1" to "0" over 6 ms or more, the device switches into external undervoltage protection mode. This mode uses two trigger levels:
  - When the XSMT pin level reaches 2 V, soft mute process begins.
  - When the XSMT pin level reaches 1.2 V, analog mute engages, regardless of digital audio level, and analog shutdown begins. (DAC and related circuitry powers down).

If XSMT is moved from "1" to "0" in 20 ns or less, then the device will interpret it as a digital controlled request to mute. It will perform a soft mute, then move to standby.

A timing diagram to show this is shown in Figure 40.

### NOTE

The XSMT input pin voltage range is from -0.3 V to DVDD+0.3 V. The ratio of external resistors must produce a voltage within this input range. Any increase in power supply (such as power supply positive noise or ripple) can pull the XSMT pin higher than DVDD+0.3 V.

For example, if the PCM510xA is monitoring a 12-V input, and dividing the voltage by 4, then the voltage at XSMT during ideal power supply conditions is 3.3 V. A voltage spike higher than 14.4 V causes a voltage greater than 3.6 V (DVDD+0.3) on the XSMT pin, potentially damaging the device.

Providing the divider is set appropriately, any DC voltage can be monitored.



# **External Power Sense Undervoltage Protection Mode (continued)**

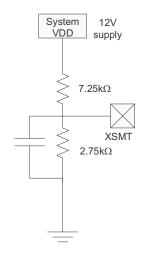


Figure 39. XSMT in External UVP Mode

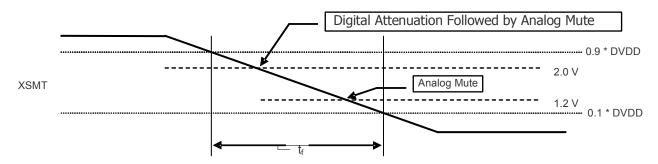


Figure 40. XSMT Timing for Undervoltage Protection

The trigger voltage values for the soft mute and hard mute are shown in Table 13. The range of values will vary from device to device, but typical thresholds are shown. XSMT should be set up to nominally be 3.3 V along with DVDD, but derived from a higher system power supply rail.

Table 13. Distribution of Voltage Thresholds

	MIN	TYP	MAX
Soft Mute Threshold Voltage	2.0 V	2.2 V	0.9×DVDD
Hard Mute Threshold Voltage	0.1×DVDD	0.9 V	1.2 V



## 11.4 Power-On Reset Function

## Power-On Reset, DVDD 3.3-V Supply

The PCM510xA includes a power-on reset function shown in Figure 41. With  $V_{DD} > 2.8$  V, the power-on reset function is enabled. After the initialization period, the PCM510xA is set to its default reset state. Analog output will begin ramping after valid data has been passing through the device for the given group delay given by the digital interpolation filter selected.

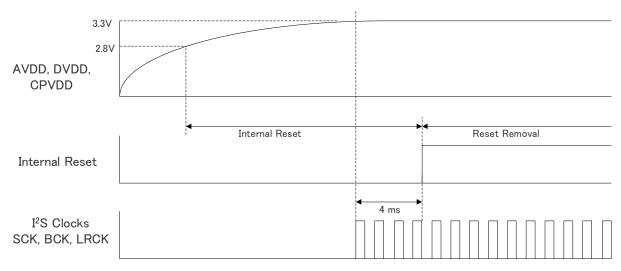


Figure 41. Power-On Reset Timing, DVDD = 3.3 V

# Power-On Reset, DVDD 1.8-V Supply

The PCM510xA includes a power-on reset function shown in Figure 42 operating at DVDD = 1.8 V. With AVDD greater than approximately 2.8 V, CPVDD greater than approximately 2.8 V, and DVDD greater than approximately 1.5 V, the power-on reset function is enabled. After the initialization period, the PCM510xA is set to its default reset state.

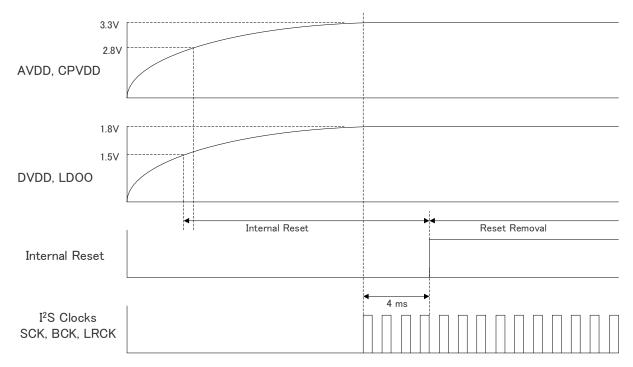


Figure 42. Power-On Reset Timing, DVDD = 1.8 V





## 11.5 PCM510xA Power Modes

## 11.5.1 Setting Digital Power Supplies and I/O Voltage Rails

The internal digital core of the PCM510xA devices run from a 1.8-V supply. This can be generated by the internal LDO, or by an external 1.8-V supply.

DVDD is used to set the I/O voltage, and to be used as the input to the onchip LDO that creates the 1.8 V required by the digital core.

For systems that require 3.3 V I/O support, but lower power consumption, DVDD should be connected to 3.3 V and LDOO can be connected to an external 1.8-V source. Doing so will disable the onchip LDO.

When setting I/O voltage to be 1.8 V, both DVDD and LDOO must be provided with an external 1.8-V supply.

## 11.5.2 Power Save Modes

The PCM510xA devices offer two power-save modes: standby and power-down.

When a clock error (SCK, BCK, and LRCK) or clock halt is detected, the PCM510xA device automatically enters standby mode. The DAC and line driver are also powered down.

When BCK and LRCK remain at a low level for more than 1 second, the PCM510xA device automatically enters powerdown mode. Power-down mode disables the negative charge pump and bias/reference circuit, in addition to those disabled in standby mode.

When expected audio clocks (SCK, BCK, LRCK) are applied to the PCM510xA device, or if BCK and LRCK start correctly while SCK remains at ground level for 16 successive LRCK periods, the device starts its powerup sequence automatically.



# 12 Layout

# 12.1 Layout Guidelines

- The PCM510xA family of devices are simple to layout. Most engineers use a shared common ground for an
  entire device. GND can be consider AGND and DGND connected.
- Good system partitioning should keep digital clock and interface traces away from the analog outputs for highest analog performance. This reduces any high speed clock return currents influencing the analog outputs.
- Power supply and charge pump decoupling capacitors should be placed as close as possible to the device.
- The top layer should be used for routing signals, whilst the bottom layer can be used for GND.

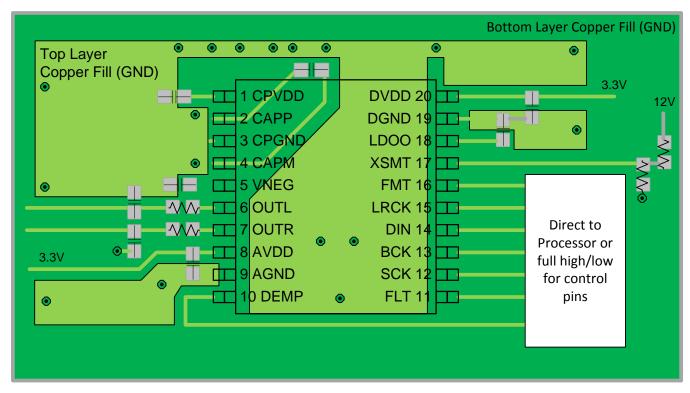


Figure 43. PCM510x Layout Example



# 13 Device and Documentation Support

## 13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 14. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
PCM5100A	Click here	Click here	Click here	Click here	Click here
PCM5101A	Click here	Click here	Click here	Click here	Click here
PCM5102A	Click here	Click here	Click here	Click here	Click here
PCM5100A-Q1	Click here	Click here	Click here	Click here	Click here
PCM5101A-Q1	Click here	Click here	Click here	Click here	Click here
PCM5102A-Q1	Click here	Click here	Click here	Click here	Click here

# 13.2 Community Resources

E2E™ Audio Converters Forum TI

**E2E Community** 

## 13.3 Trademarks

Directpath is a trademark of Texas Instruments, Inc. System Two Cascade, Audio Precision are trademarks of Audio Precision.

# 13.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

# 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, see the left-hand navigation.

## 14.1 Mechanical Data





7-May-2015

## PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
PCM5100APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5100A	Samples
PCM5100APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5100A	Samples
PCM5100AQPWRQ1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	P5100AQ1	Samples
PCM5101APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5101A	Samples
PCM5101APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5101A	Samples
PCM5101AQPWRQ1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	P5101AQ1	Samples
PCM5102APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5102A	Samples
PCM5102APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5102A	Samples
PCM5102AQPWRQ1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	P5102AQ1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.





7-May-2015

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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## OTHER QUALIFIED VERSIONS OF PCM5100A, PCM5100A-Q1, PCM5101A, PCM5101A-Q1, PCM5102A, PCM5102A-Q1:

- Catalog: PCM5100A, PCM5101A, PCM5102A
- Automotive: PCM5100A-Q1, PCM5101A-Q1, PCM5102A-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

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# TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PCM5100APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5100AQPWRQ1	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5101APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5101AQPWRQ1	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5102APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5102AQPWRQ1	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PCM5100APWR	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5100AQPWRQ1	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5101APWR	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5101AQPWRQ1	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5102APWR	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5102AQPWRQ1	TSSOP	PW	20	2000	367.0	367.0	38.0

PW (R-PDSO-G20)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



# PW (R-PDSO-G20)

# PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
  C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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